

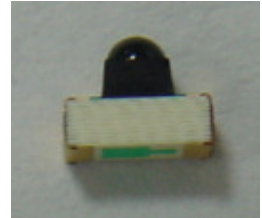
Technical Data Sheet

1.6mm Round Subminiature Side Looking Phototransistor

PT26-71B/T/TR8(HG)

Features

- Fast response time
- High photo sensitivity
- Small junction capacitance
- Package in 8mm tape on 7" diameter reels.
- Pb free
- The product itself will remain within RoHS compliant version.



Descriptions

- PT26-71B/T/TR8(HG) is a phototransistor in miniature SMD package which is molded in a black with spherical top view lens. The device is Spectrally matched to infrared emitting diode.

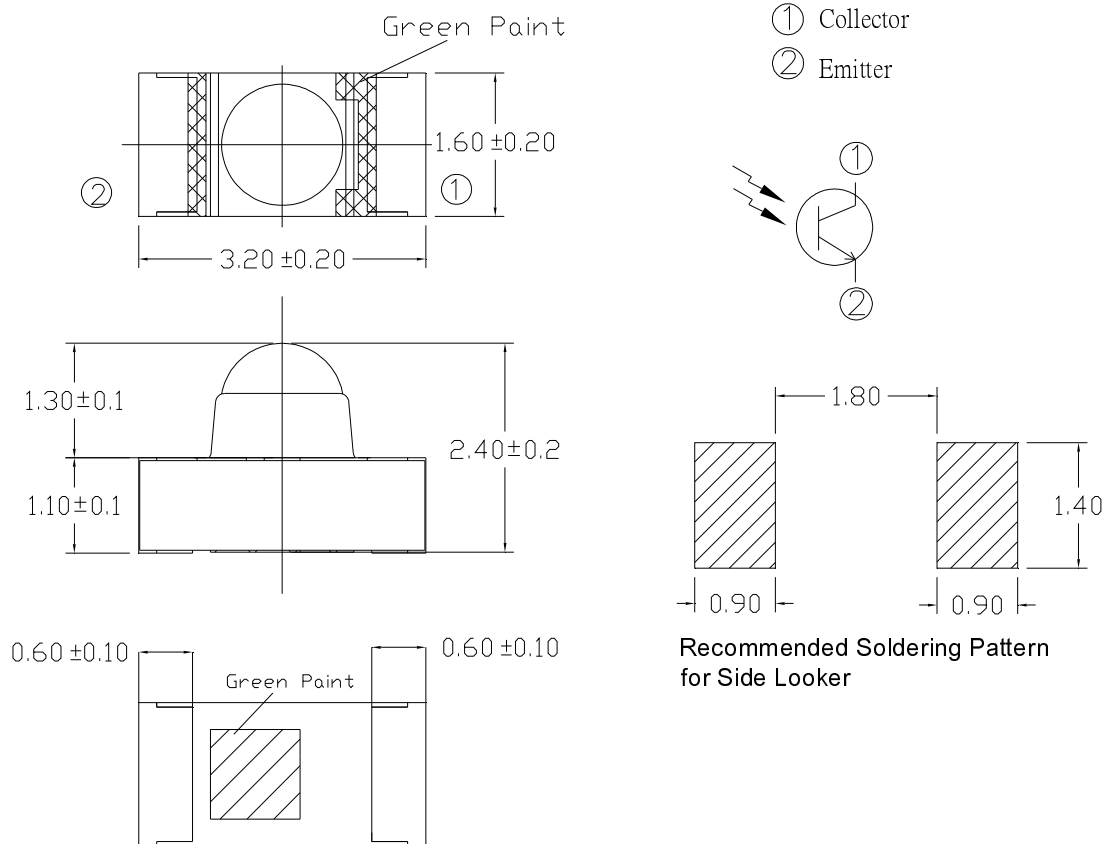
Applications

- Miniature switch
- Counters and sorter
- Position sensor
- Infrared applied system

Device Selection Guide

LED Part No.	Chip	Lens Color
	Material	
PT26-71B/T/TR8(HG)	Silicon	Black

Package Dimensions



Notes: 1.All dimensions are in millimeters

2.Tolerances unless dimensions ± 0.1 mm

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Units
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector-Voltage	V_{ECO}	5	V
Collector Current	I_C	20	mA
Operating Temperature	T_{opr}	-25 ~ +85	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^\circ\text{C}$
Soldering Temperature	T_{sol}	260	$^\circ\text{C}$
Power Dissipation at(or below) 25 $^\circ\text{C}$ Free Air Temperature	P_c	75	mW

Notes: *1:Soldering time ≤ 5 seconds.

PT26-71B/T/TR8(HG)

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Rang Of Spectral Bandwidth	$\lambda_{0.1}$	---	730	---	1100	nm
Wavelength Of Peak Sensitivity	λ_P	---	---	940	---	nm
Collector-Emitter Breakdown Voltage	BV_{CEO}	$I_C=100\mu A$ $E_e=0mW/cm^2$	30	---	---	V
Emitter-Collector Breakdown Voltage	BV_{ECO}	$I_E=100\mu A$ $E_e=0mW/cm^2$	5	---	---	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=1.5mA$ $E_e=1mW/cm^2$	---	---	0.4	V
Collector Dark Current	I_{CEO}	$V_{CE}=20V$ $E_e=0mW/cm^2$	---	---	100	nA
On State Collector Current	$I_{C(ON)}$	$V_{CE}=5V$ $E_e=1mW/cm^2$ $\lambda_P=940nm$	1.14	3.0	10.00	mA
Rise Time	t_r	$V_{CE}=5V$ $I_C=1mA$ $R_L=1000\Omega$	---	15	---	μS
Fall Time	t_f		---	15	---	
View Angle	$2\theta_{1/2}$	$V_{CE}=5V$	---	50	---	deg

Rankings

Rank	Symbol	Min	Max	Unit	Test Condition
BIN4	$I_{C(ON)}$	1.14	2.60	mA	$V_{CE}=5V$ $E_e=1mW/cm^2$ $\lambda_P=940nm$
BIN5		1.77	3.61		
BIN6		2.67	5.07		
BIN7		3.54	7.07		
BIN8		5.00	10.00		

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Typical Electro-Optical Characteristics Curves

Fig.1 Collector Power Dissipation vs. Ambient Temperature

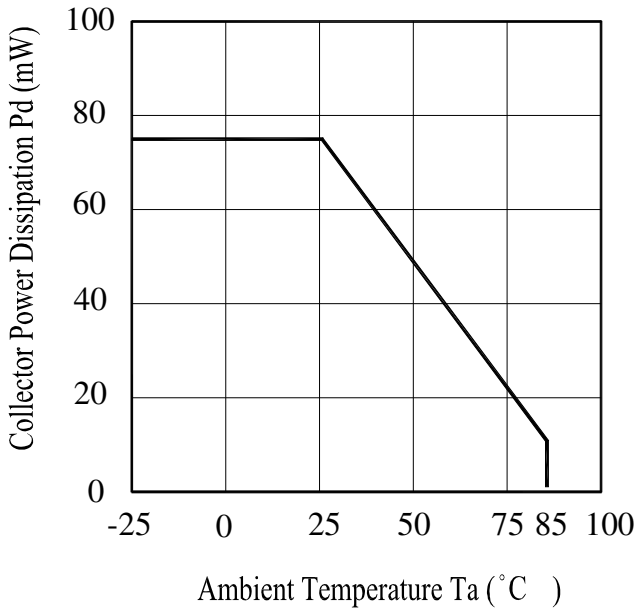


Fig.2 Spectral Sensitivity

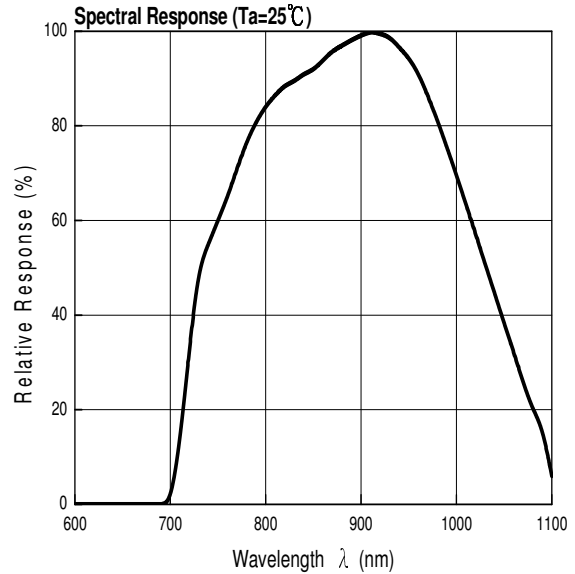


Fig.3 Collector Dark Current vs. Ambient Temperature

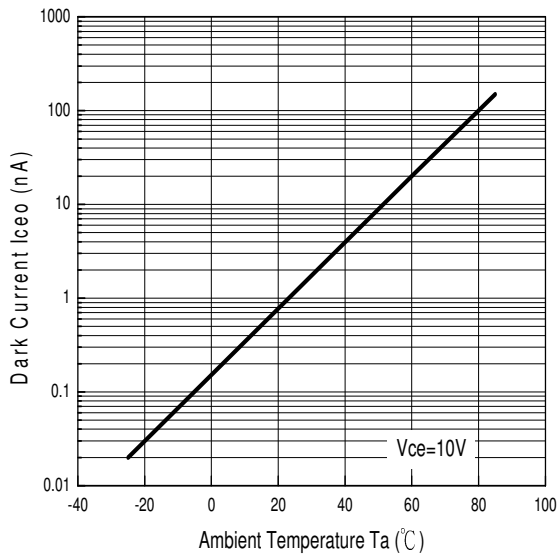


Fig.4 Collector Current vs. Irradiance

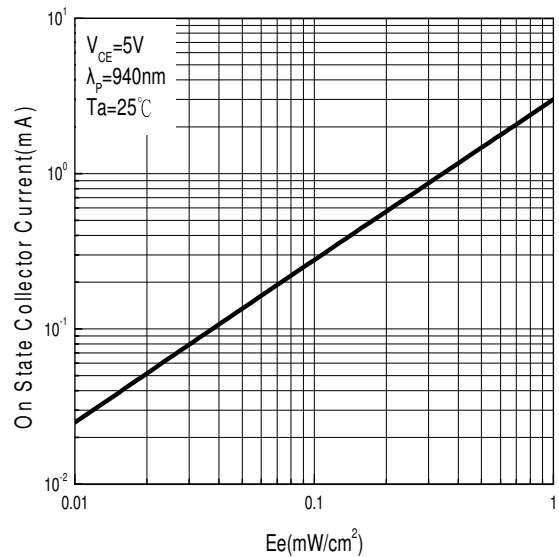


Fig.5 Switching Time vs. Load Resistance

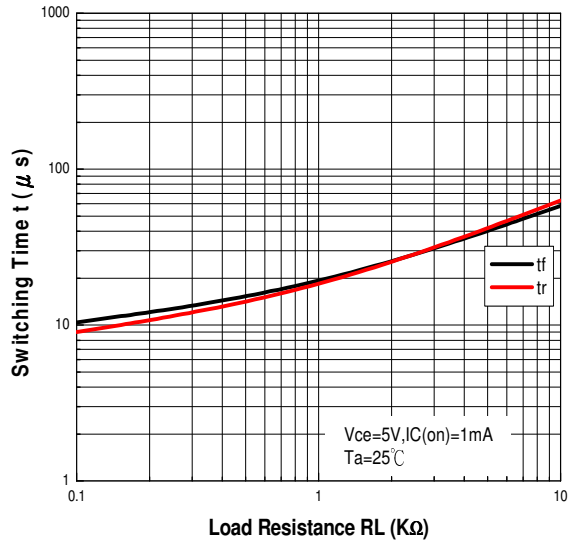
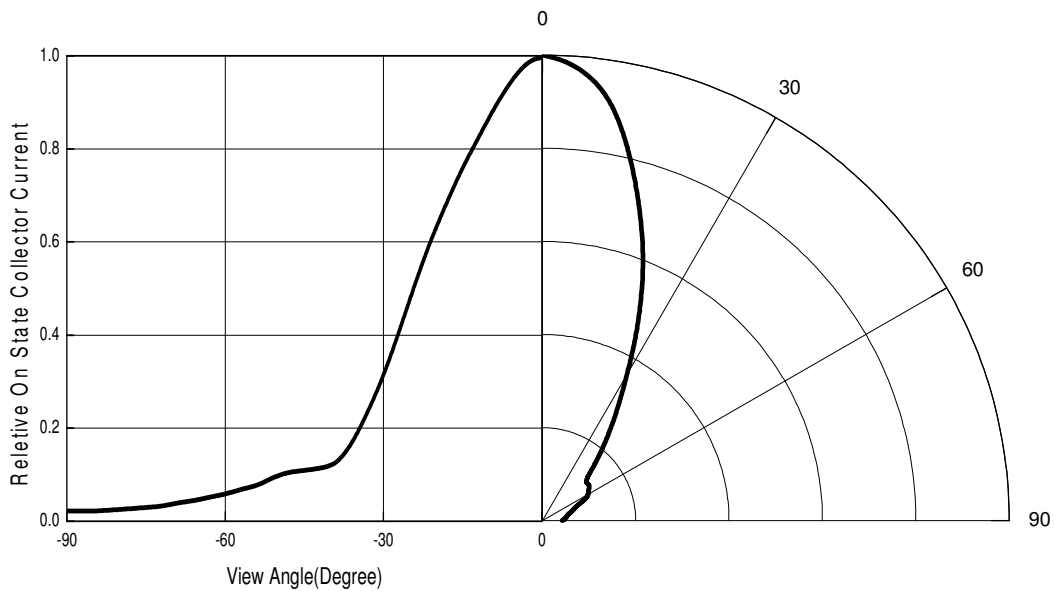


Fig.6 Relative On State Collector Current vs. Angular Displacement



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

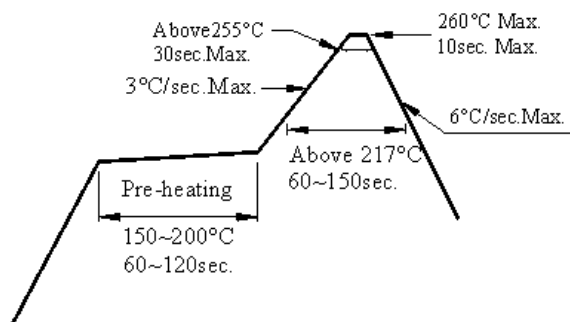
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

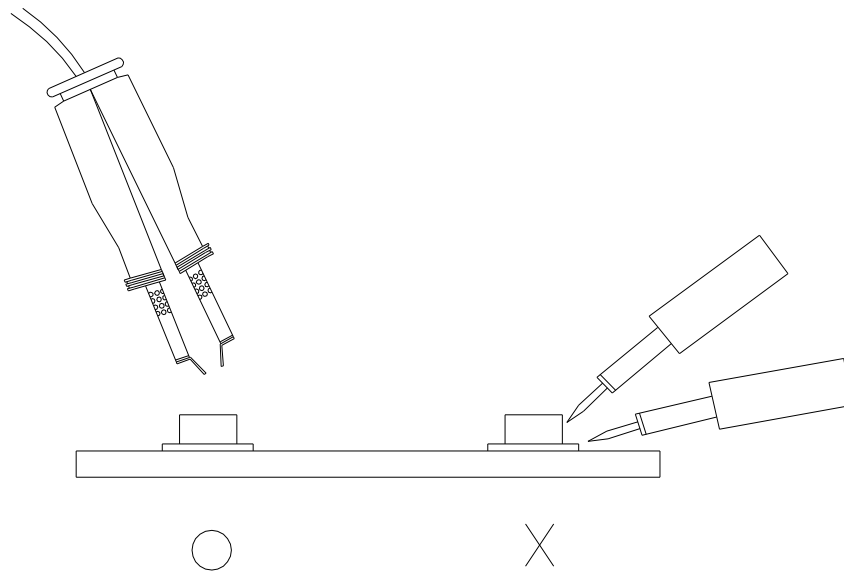
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

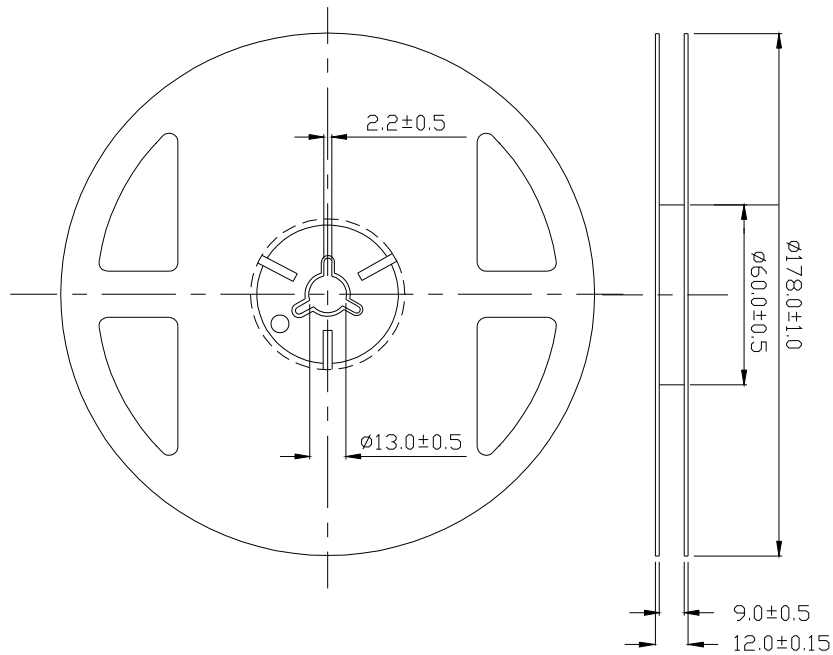
5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



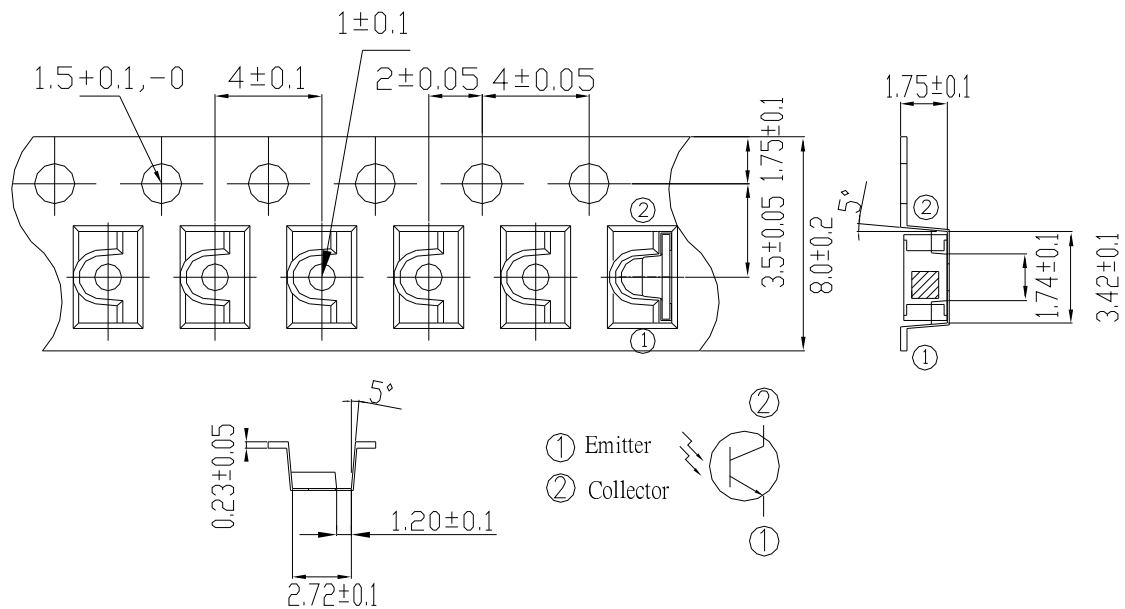
Package Dimensions

1. Reel Dimensions



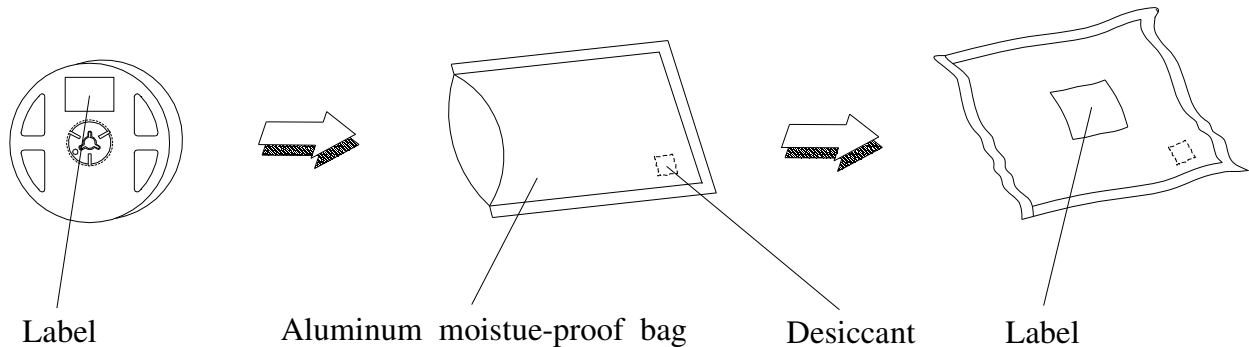
Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

2. Carrier Tape Dimensions :(Quantity: 1500pcs/reel)

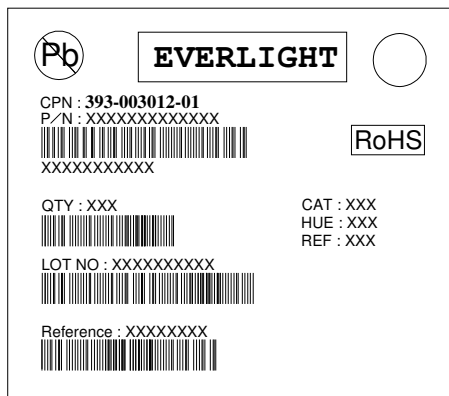


Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Packing Procedure



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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